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Portwell PCOM-BA02GL

pic:



pn:
: PCOM-BA02GL

formfactor:
: COM Express Type 10

manufacturer:
: Portwell

cpu:
: Intel Atom x6000E

emmc:
: 16/32 GB

ram:
: 4/8/16 GB LPDDR4

temprange:
: 0...+60 °C, -40...+85 °C

edp:
: 1 (or LVDS)

dp:
: 1 DP/HDMI/VDI

lvd:
: Single Channel via eDP<>LVDS IC (or eDP)

ethernet:
: 1 (1GBit? 2.5 GBit?, SGMII? PCIe?) (GPY215? I210AT?)

dsi:
: -

csi:
: -

usb2:
: 6(8)

usb3:
: 2

can:
: -?

uart:
: 2 from EC

spi:
: + (BIOS, TPM 2.0)

pcie:
: x4 x 1, x2 x 2, x1 x 4 gen 3

i2:
: HDA

i2c:
: 1 (from EC\CPU)

smbu:

1 (from EC\CPU)

gpio:

4 GPI, 4 GPO from EC (or SDIO 3.0 from CPU option)

bmc:

EC (IT5121VG-I-128)

tpm:

TPM 2.0

sata:

2 SATA III

sdio:

SDIO 3.0 (option)

bio:

AMI BIOS

dimension:

84 x 55 mm

lpc:

+ (eSPI<>LPC ECE1200????)

espi:

-

datasheetwww:

link

datasheet:

link

struct:

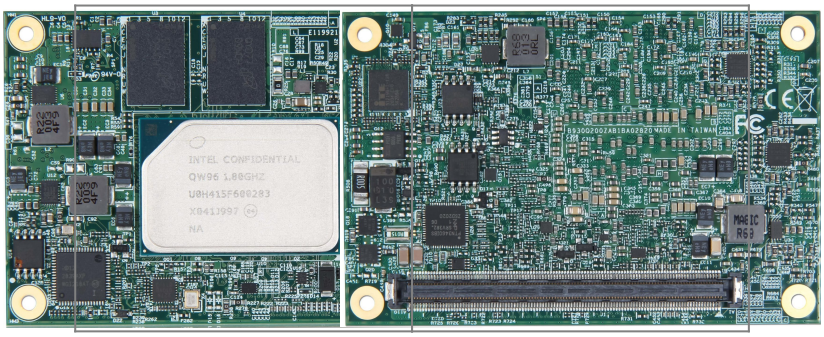


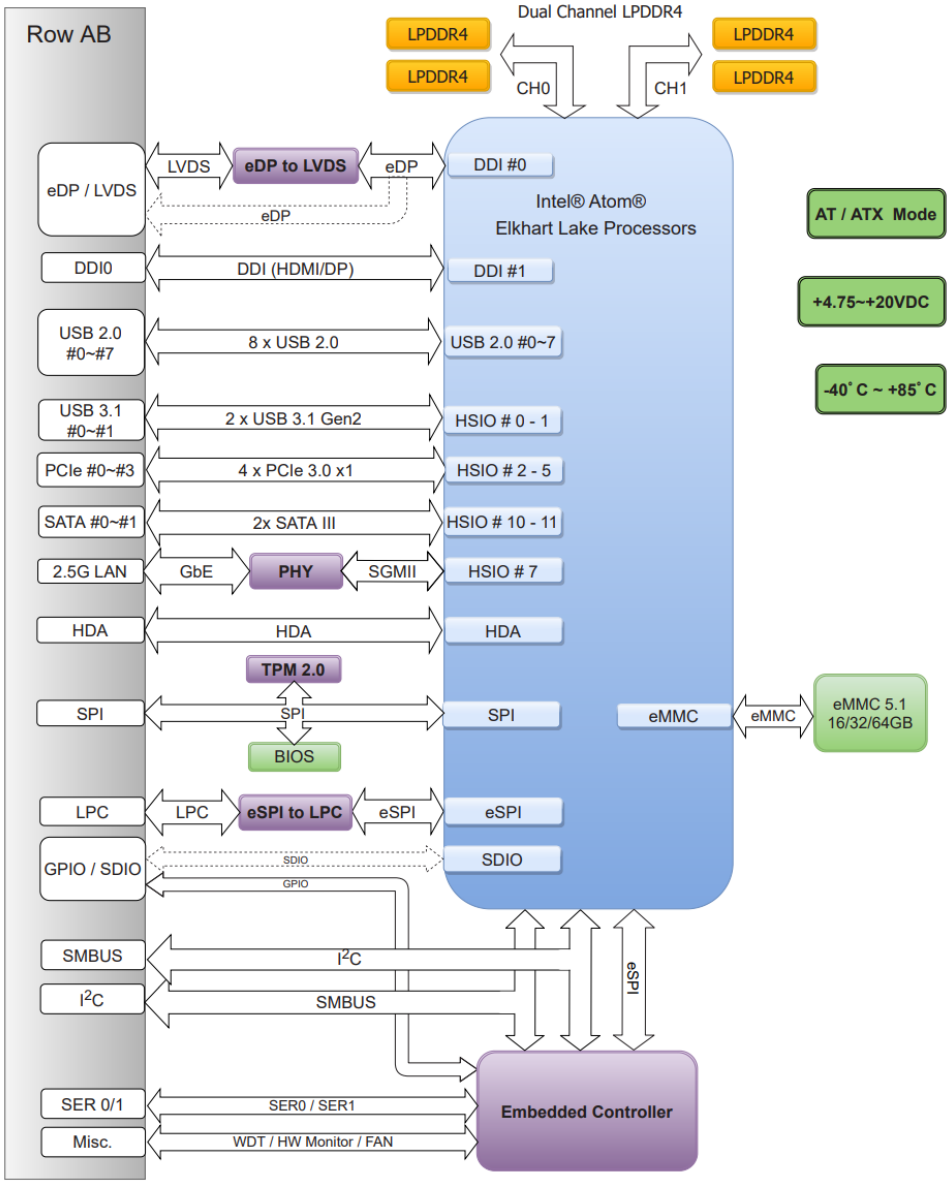
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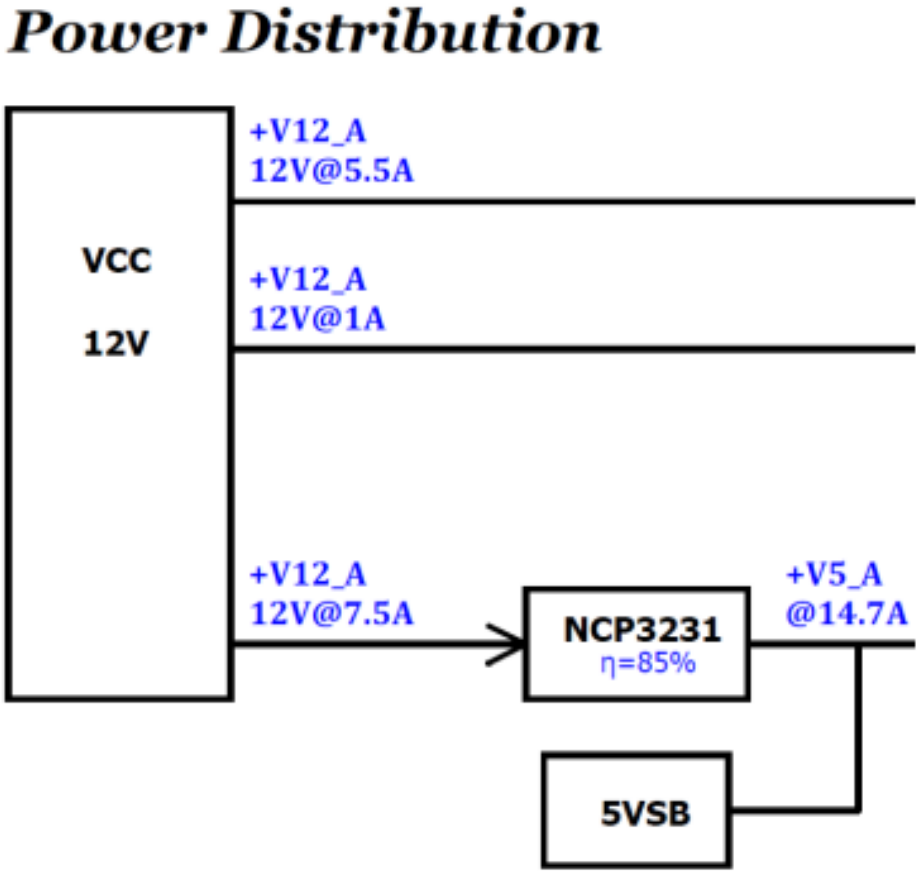
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power:

4.75V to 20V, AT/ATX Mode




Row AB
Dual Channel LPDDR4
LPDDR4
LPDDR4
LPDDR4
LPDDR4
CH0
CH1
eDP / LVDS
LVDS
eDP to LVDS
eDP
eDP
DDI #0
Intel® Atom®
Elkhart Lake Processors
AT / ATX Mode
DDI0
DDI (HDMI/DP)
DDI #1
+4.75~+20VDC
USB 2.0
#0~#7
8 x USB 2.0
USB 2.0 #0~7
-40˚C ~ +85˚C
USB 3.1
#0~#1
2 x USB 3.1 Gen2
HSIO # 0 - 1
PCIe #0~#3
4 x PCIe 3.0 x1
HSIO # 2 - 5
SATA #0~#1
2x SATA III
HSIO # 10 - 11
2.5G LAN
GbE
PHY
SGMII
HSIO # 7
HDA
HDA
HDA
TPM 2.0
SPI
SPI
SPI
eMMC
eMMC
eMMC 5.1
16/32/64GB
BIOS
LPC
LPC
eSPI to LPC
eSPI
eSPI
GPIO / SDIO
SDIO
SDIO
GPIO
SMBUS
I2C
I2C
SMBUS
eSPI
SER 0/1
SER0 / SER1
Misc.
WDT / HW Monitor / FAN
Embedded Controller



docs

PCOM-BA02GL	Portwell	SOM flyer	link
PCOM-BA02GL	Portwell	User's guide	link
PTN3460	NXP	eDP<>LVDS bridge	link
IT5121VG-I-128	ITE	EC	
ECE1200	Microchip	eSPI<>LPC	link

USB

USB 0	HSIO 0	from XHCI controller
USB 1	HSIO 1	from XHCI controller

PCIe

PCIE0	HSIO 2
PCIE1	HSIO 3
PCIE2	HSIO 4
PCIE3	HSIO 5

SATA

SATA0	HSIO 10
SATA1	HSIO 11

LPC

LPC Bus is supported by a eSPI-to-LPC bridge IC